



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD60R950C6		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005339750						
<b>Package</b>		PG-TO252-3-341		<b>Weight*</b>		387.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.144	0.55	0.55	5526	5526
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		177	
	non noble metal	iron	7439-89-6	0.229	0.06		591	
	non noble metal	copper	7440-50-8	228.946	59.04	59.12	590147	590915
	non noble metal	aluminium	7429-90-5	0.400	0.10	0.10	1032	1032
wire	non noble metal	aluminium	7429-90-5	0.400	0.10	0.10	1032	1032
encapsulation	organic material	carbon black	1333-86-4	0.391	0.10		1009	
	plastics	epoxy resin	-	11.872	3.06		30602	
	inorganic material	silicondioxide	60676-86-0	118.200	30.47	33.63	304678	336289
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9641	9641
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1312	1312
solder	non noble metal	tin	7440-31-5	0.045	0.01		116	
	noble metal	silver	7440-22-4	0.056	0.01		145	
	non noble metal	lead	7439-92-1	2.144	0.55	0.57	5527	5788
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		49	
	non noble metal	copper	7440-50-8	19.177	4.94	4.94	49433	49497
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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